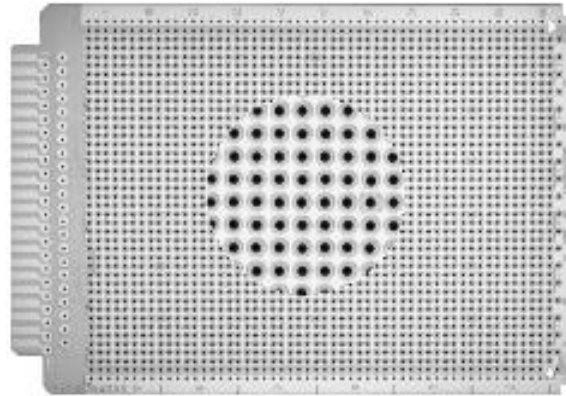


**3662**

**4.5" x 6.5"**

**Circuit Pattern:** Contacts Only  
**Contacts:** 22/44 @ .156 Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 50  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- Unrestricted component placement over entire board surface
- Layout paper and instructions included
- Row and column legend provided

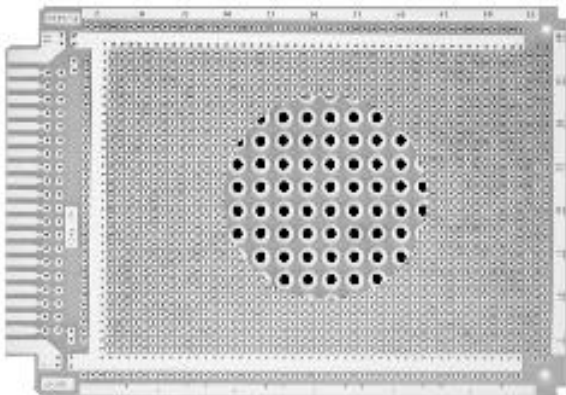


**3662A6**

**4.5" x 6.5"**

**Circuit Pattern:** Ground Plane  
**Contacts:** 22/44 @ .156" Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 90  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- 0.085" diameter clearance area around holes
- Ground plane on component side; wiring side has contacts only
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Plane surface is solder-coated for user convenience
- Layout paper and instructions included
- Row and column legend provided



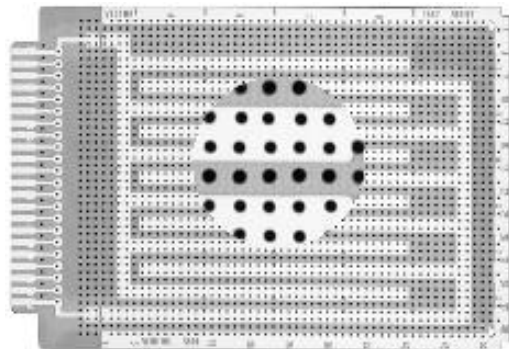
**3662-9**

**4.5" x 6.5"**

**Circuit Pattern:** Pad-Per-Hole  
**Contacts:** 22/44 @ .156" Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 48  
**Material:** FR4 Epoxy Glass  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- 0.080" diameter, isolated solder pad around holes, both sides
- Pad and bus surfaces solder-coated for quick, convenient soldering
- Row and column legends provided
- Layout paper and instructions included

Products



**3682-2**

**4.5" x 6.5"**

**Circuit Pattern:** Interleaved Buses  
**Contacts:** 22/44 @ .156" Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 24  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

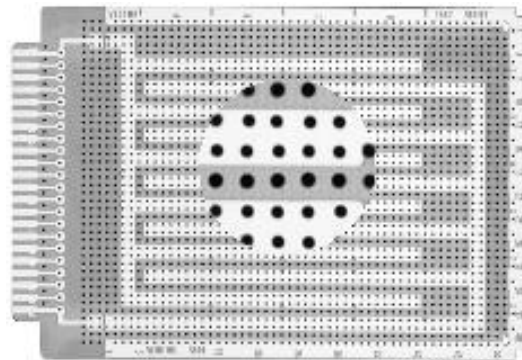
- Bus pattern on wiring side, solder-coated for user convenience
- Bus outline traced on component side to facilitate component placement
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacing
- Unclad test point area at top of board
- Layout paper and instructions included
- Row and column legends provided

**Note:** Same as 3682-4 but without Ground Plane

## 3682-4 4.5" x 6.5"

**Circuit Pattern:** Interleaved Bus/  
Ground Plane  
**Contacts:** 22/44 @ .156" Ctrs,  
Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 24  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

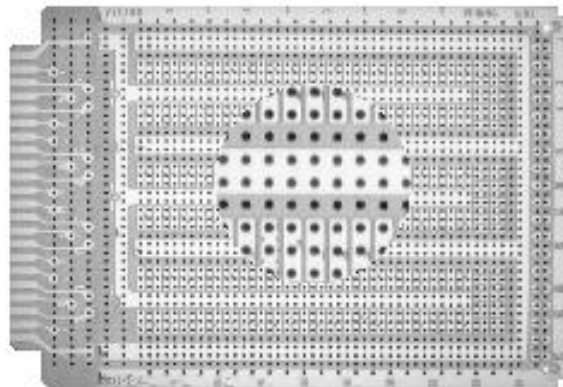
- Power bus in rows across component side; overall ground plane on wiring side
- 0.085" etched clearance area around each hole on ground plane side
- Bus and plane surfaces solder coated for user convenience
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Layout paper and instructions included
- Row and column legends provided



## 3677-2 4.5" x 6.5"

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** 22/44 @ .156" Ctrs.  
Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 12  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

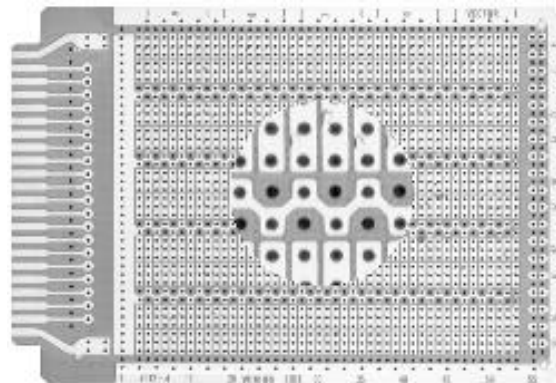
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Voltage/ground buses interleaved between pad areas on wiring side
- Row and column legends provided
- Test point area, with solder pads around holes, provided along back edge of board
- Layout paper and instructions included



## 4112-4 4.5" x 6.5"

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** 22/44 @ .156" Ctrs,  
Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 25  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

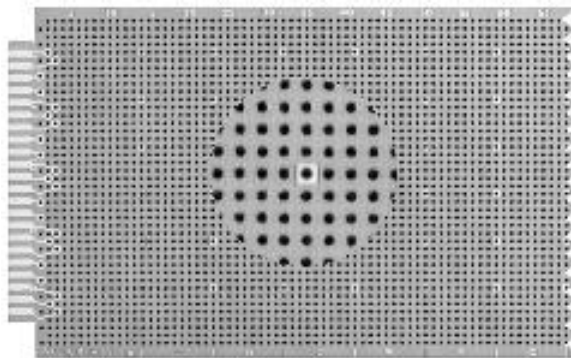
- Continuous ground plane on component side with 0.085" clearance pad around each hole
- 3-hole solder pads (0.28 x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included

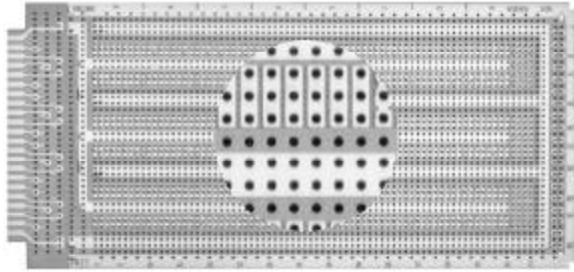


## 3662-2 4.5" x 9.6"

**Circuit Pattern:** Contacts Only  
**Contacts:** 22/44 @ .156" Ctrs,  
Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 90  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690-6  
**Rec. Card Cage:** Series 14  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- Unrestricted component placement over entire board surface
- Row and column legends provided
- Layout paper and instructions included



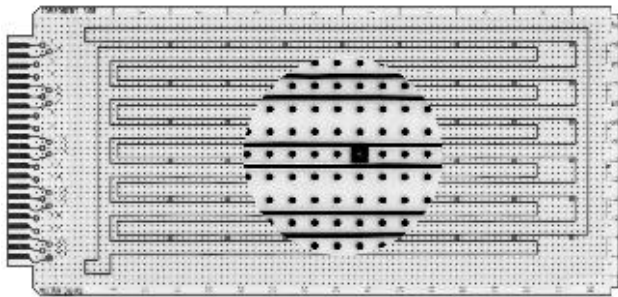


### 3677

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** 22/44 @ .156" Ctrs., Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 21  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 14  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

### 4.5" x 9.6"

- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included

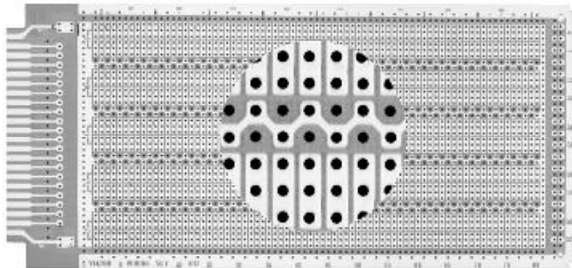


### 3682

**Circuit Pattern:** Interleaved Buses  
**Contacts:** 22/44 @ .156 Ctrs., Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 48  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690-6  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

### 4.5" x 9.6"

- Etched bus pattern on wiring side, solder-coated for user convenience
- Bus outlines traced on component side
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacings
- Layout paper and instructions included
- Row and column legends provided



### 4112

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** 22/44 @ .156" Ctrs., Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 40  
**Material:** FR4 Epoxy Glass  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690-6  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

### 4.5" x 9.6"

- Zig-zag bus pattern on wiring side provides access to voltage or ground at alternating hole positions
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Continuous ground plane on component side with 0.085" etched clearance area around each hole
- Layout paper and instructions included
- Row and column legends provided